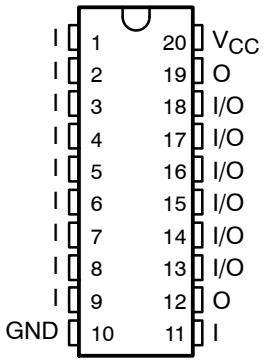
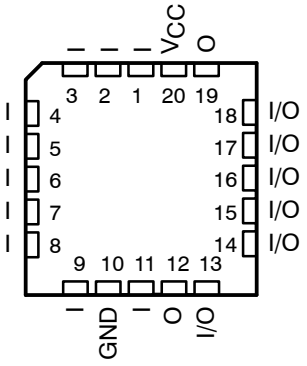
- **High-Performance Operation:**
  Propagation Delay . . . 15 ns Max
- **Power-Up Clear on Registered Devices (All Register Outputs are Set High, but Voltage Levels at the Output Pins Go Low)**
- **Package Options Include Ceramic Flat (W) Packages, Ceramic Chip Carriers (FK), and Ceramic (J) 300-mil DIPs**
- **Dependable Texas Instruments Quality and Reliability**

DEVICE	I INPUTS	3-STATE O OUTPUTS	REGISTERED Q OUTPUTS	I/O PORTS
PAL16L8	10	2	0	6
PAL16R4	8	0	4 (3-state buffers)	4
PAL16R6	8	0	6 (3-state buffers)	2
PAL16R8	8	0	8 (3-state buffers)	0

TIBPAL16L8'
J OR W PACKAGE
(TOP VIEW)



TIBPAL16L8'
FK PACKAGE
(TOP VIEW)



Pin assignments in operating mode

description

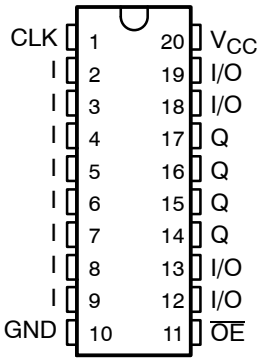
These programmable array logic devices feature high speed and functional equivalency when compared with currently available devices. These IMPACT-X™ circuits combine the latest Advanced Low-Power Schottky technology with proven titanium-tungsten fuses to provide reliable, high-performance substitutes for conventional TTL logic. Their easy programmability allows for quick design of custom functions and typically results in a more compact circuit board. In addition, chip carriers are available for futher reduction in board space.

The TIBPAL16' M series is characterized for operation over the full military temperature range of –55°C to 125°C.

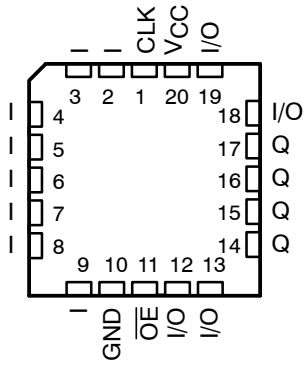
IMPORTANT PROGAMMING NOTE: For TIBPAL16L8–15M devices in J, W, or FK packages – For date code 9903A or later device programming, select from either **TI Military/16L8–12** or TI commercial **TI/16L8–10** on the Manufacturer/Device menu listing in your programming system.

IMPORTANT PROGAMMING NOTE: For TIBPAL16R4–15M devices in J, W, or FK packages – For date code 9616A or later device programming, select from either **TI Military/16R4–12** or TI commercial **TI /16R4–10** on the Manufacturer/Device menu listing in your programming system.

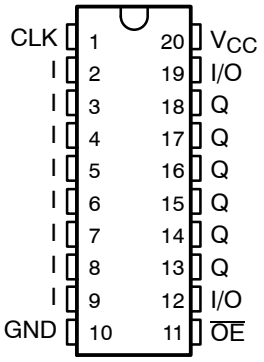
TIBPAL16R4'
J OR W PACKAGE
(TOP VIEW)



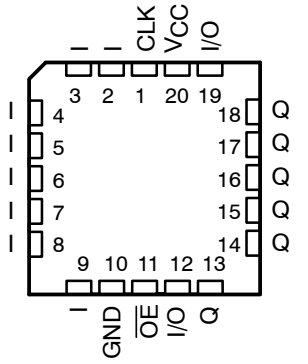
TIBPAL16R4'
FK PACKAGE
(TOP VIEW)



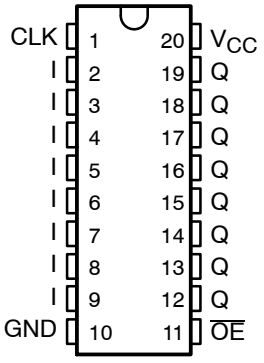
TIBPAL16R6'
J OR W PACKAGE
(TOP VIEW)



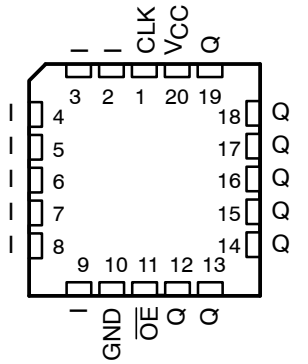
TIBPAL16R6'
FK PACKAGE
(TOP VIEW)



TIBPAL16R8'
J OR W PACKAGE
(TOP VIEW)



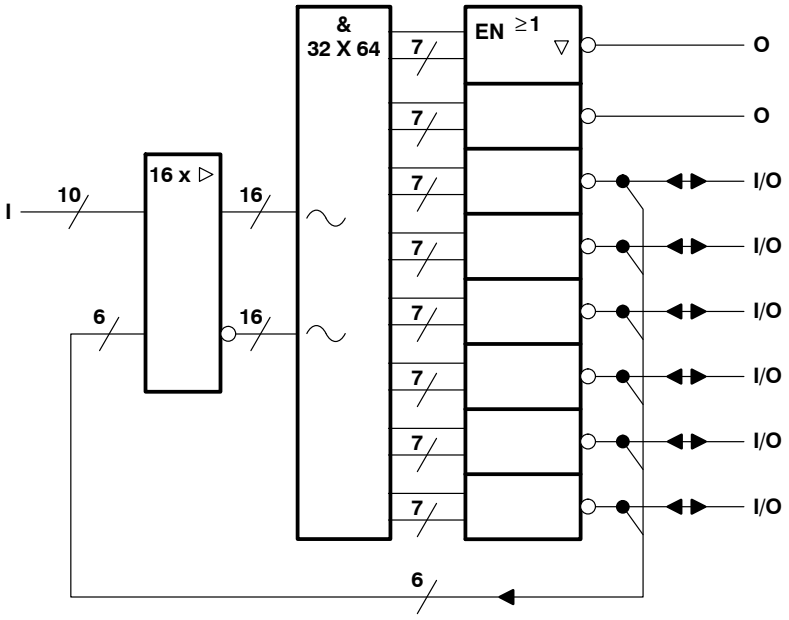
TIBPAL16R8'
FK PACKAGE
(TOP VIEW)



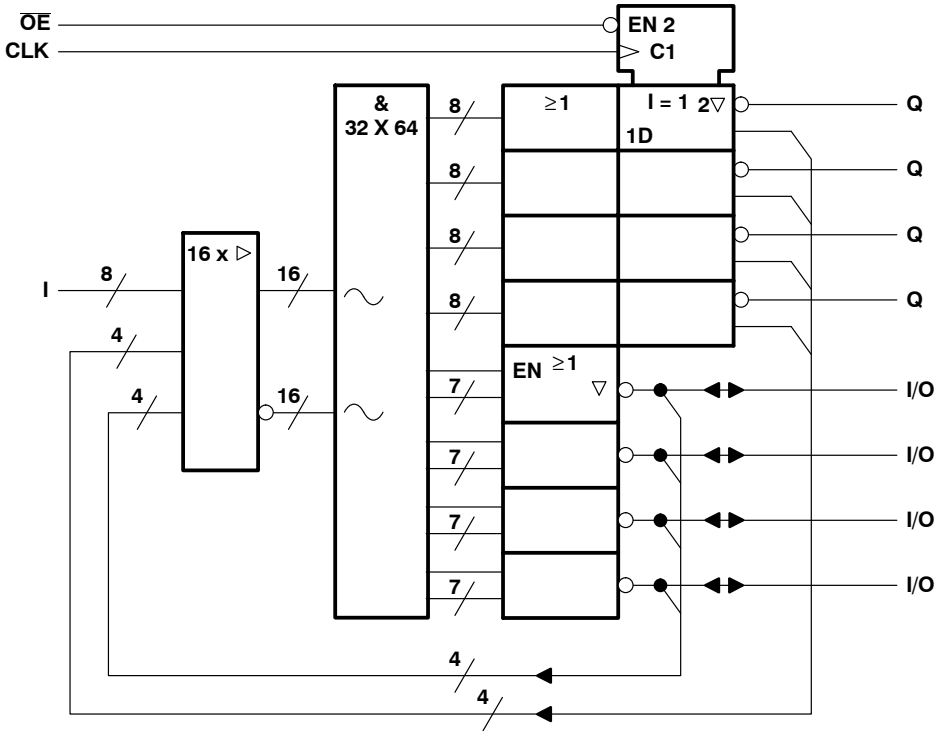
Pin assignments in operating mode

functional block diagrams (positive logic)

TIBPAL16L8'



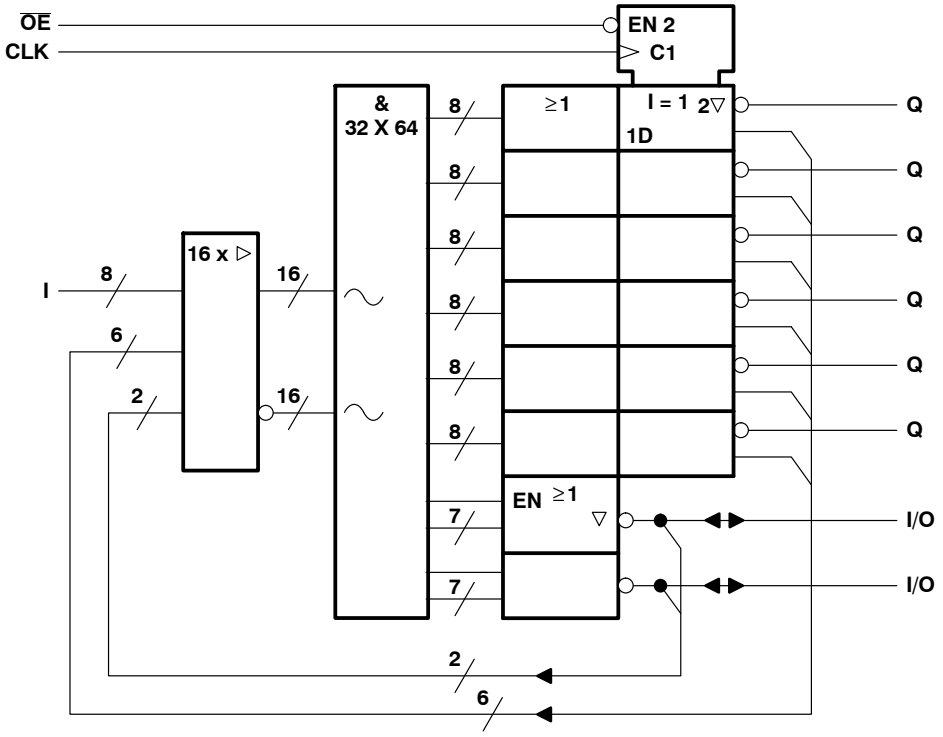
TIBPAL16R4'



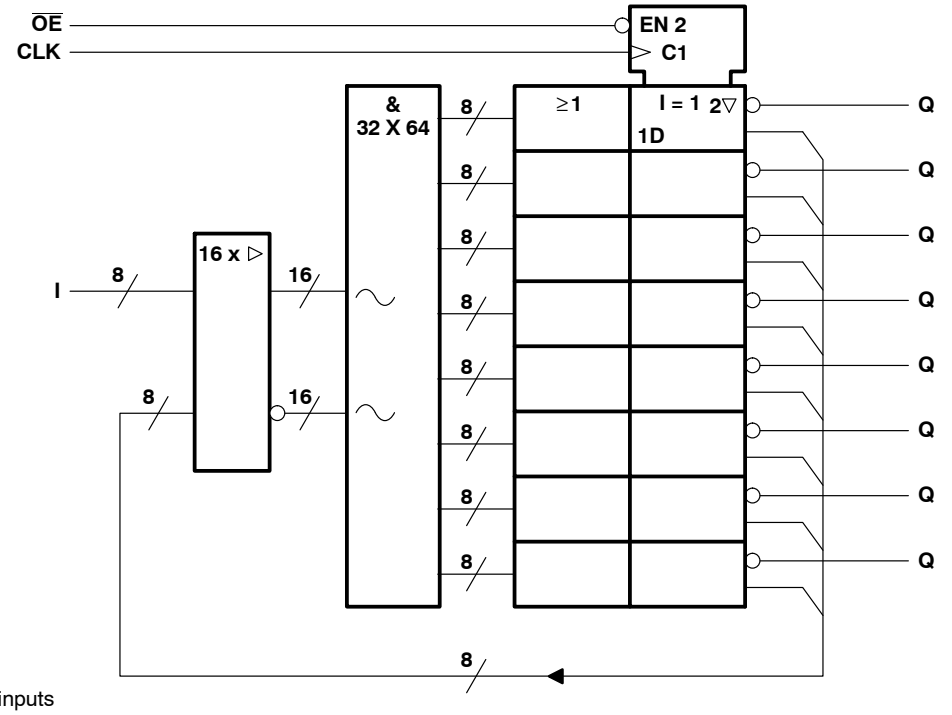
denotes fused inputs

functional block diagrams (positive logic)

TIBPAL16R6'

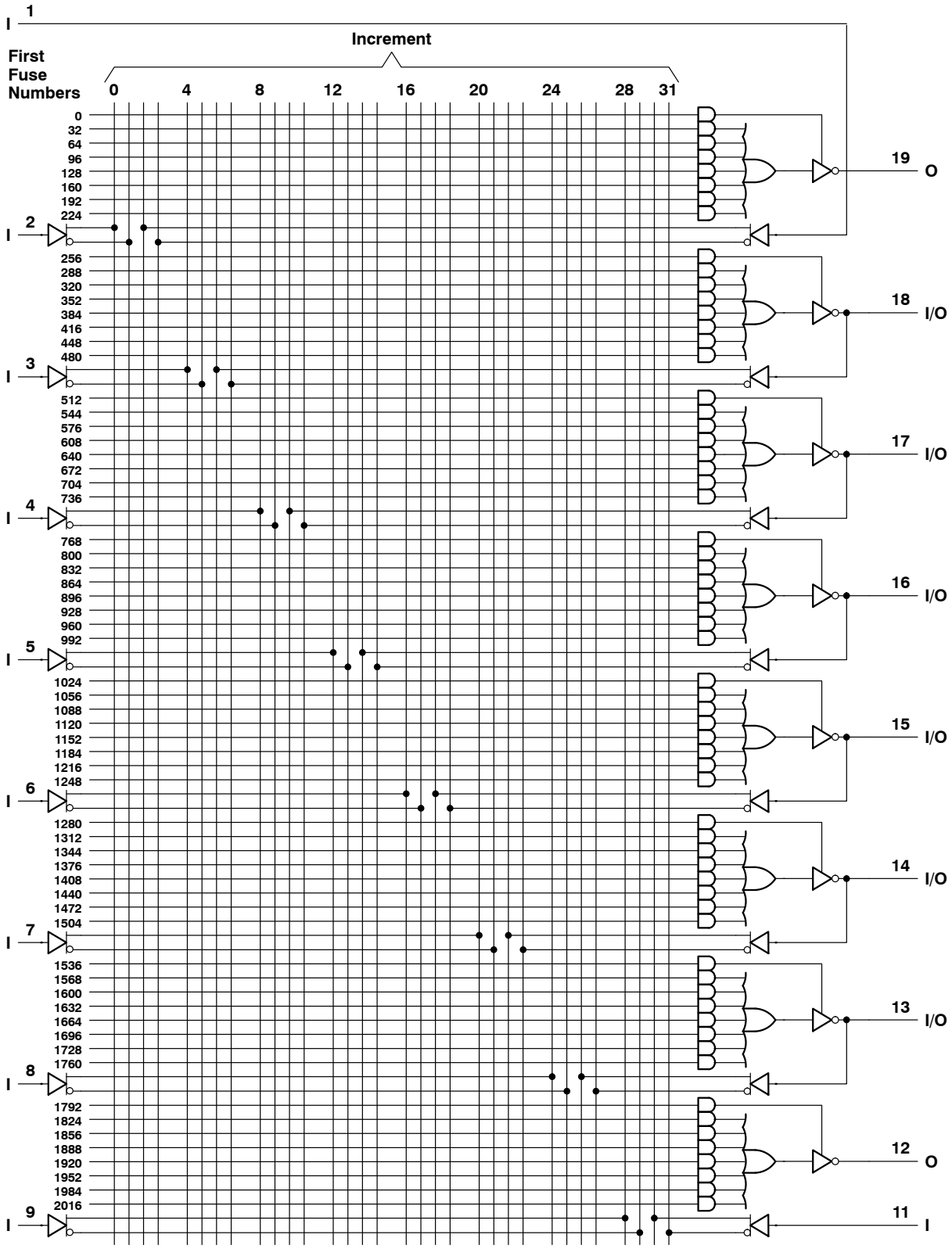


TIBPAL16R8'



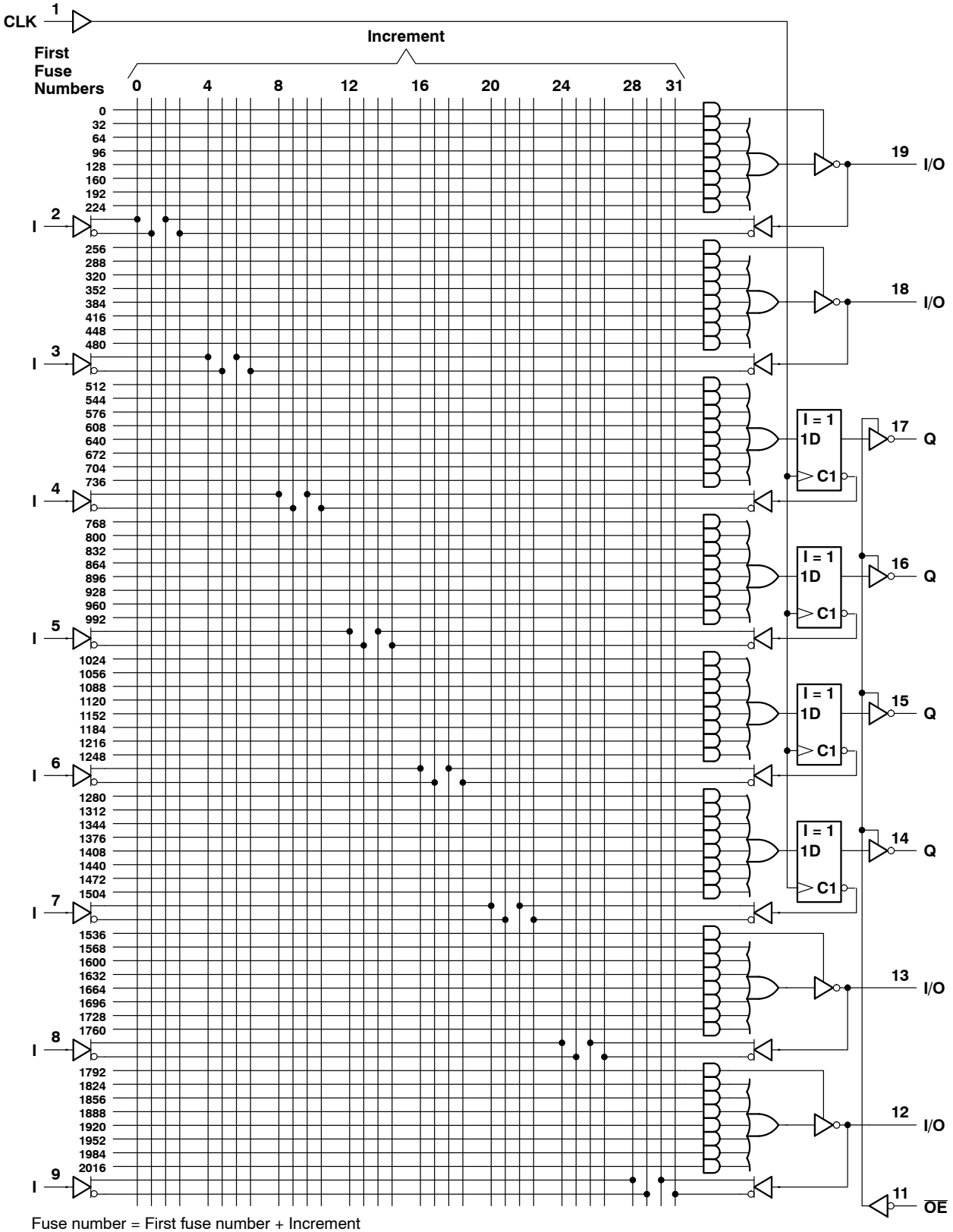
denotes fused inputs

TIBPAL16L8-15M logic diagram (positive logic)



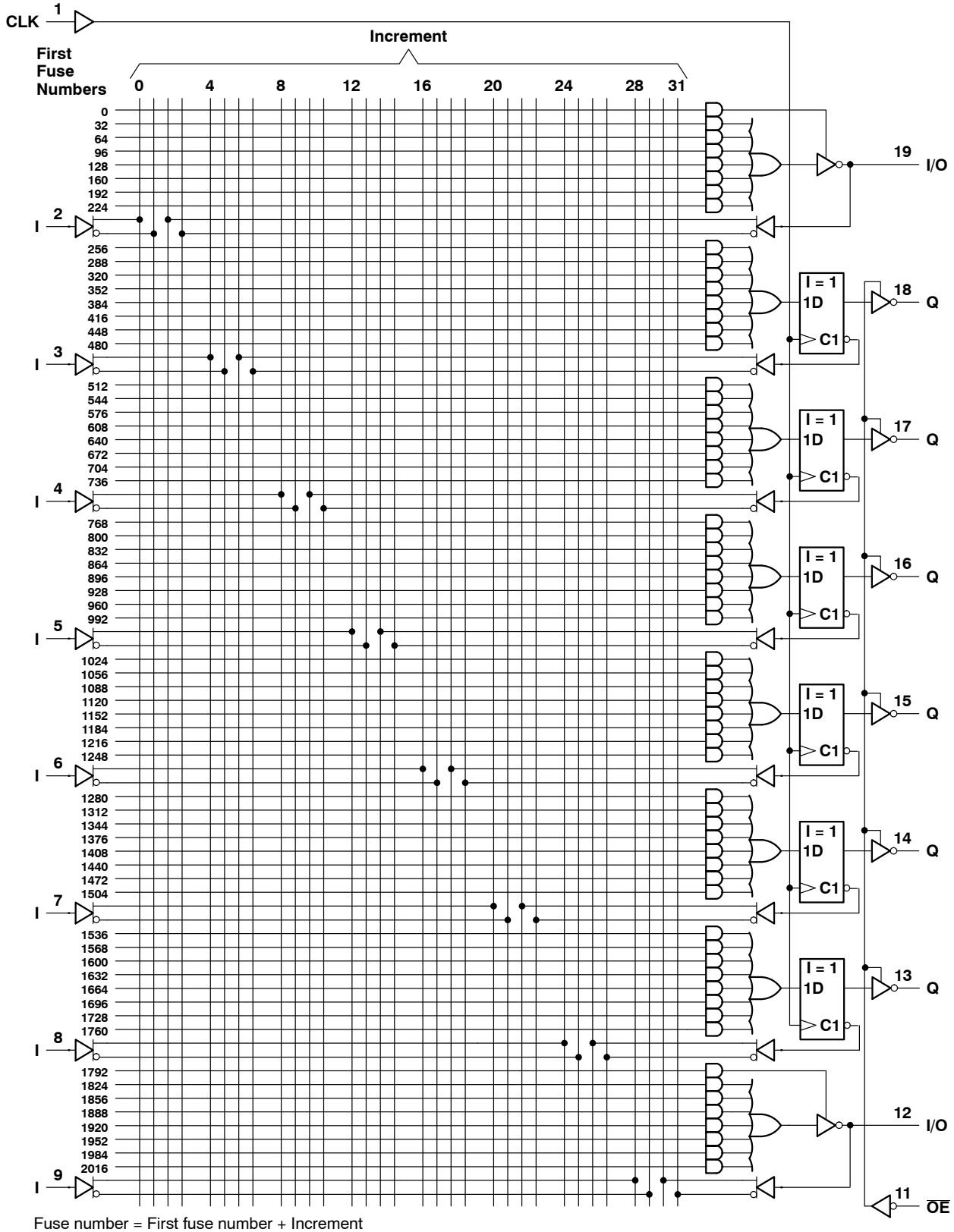
Fuse number = First fuse number + Increment

TIBPAL16R4-15M logic diagram (positive logic)



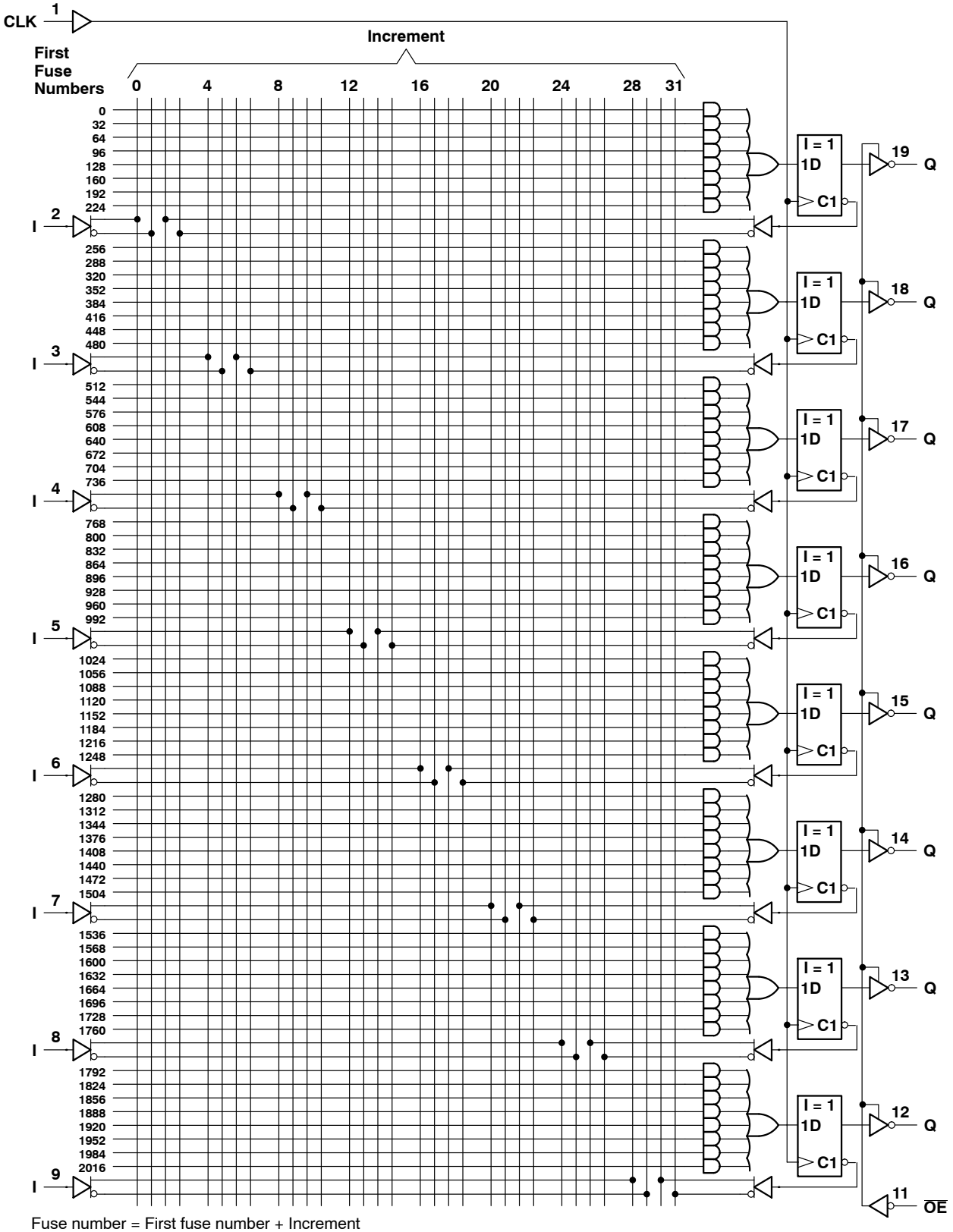
Fuse number = First fuse number + Increment

TIBPAL16R6-15M logic diagram (positive logic)



Fuse number = First fuse number + Increment

TIBPAL16R8-15M logic diagram (positive logic)



Fuse number = First fuse number + Increment

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage (see Note 1) . . . . . 5.5 V
Voltage applied to disabled output (see Note 1) . . . . . 5.5 V
Operating free-air temperature range . . . . . –55°C to 125°C
Storage temperature range . . . . . –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: These ratings apply except for programming pins during a programming cycle.

recommended operating conditions

			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage		4.5	5	5.5	V
V_{IH}	High-level input voltage		2		5.5	V
V_{IL}	Low-level input voltage				0.8	V
I_{OH}	High-level output current				–2	mA
I_{OL}	Low-level output current				12	mA
f_{clock}	Clock frequency		0		50	MHz
t_w	Pulse duration, clock (see Note 2)	High	9			ns
		Low	10			
t_{su}	Setup time, input or feedback before clock↑		15			ns
t_h	Hold time, input or feedback after clock↑		0			ns
T_A	Operating free-air temperature		–55	25	125	°C

NOTE 2: The total clock period of clock high and clock low must not exceed clock frequency, f_{clock}. The minimum pulse durations specified are only for clock high or low, but not for both simultaneously.

electrical characteristics over recommended operating free-air temperature range

PARAMETER		TEST CONDITIONS			TIBPAL16R4-15M			UNIT
					MIN	TYP‡	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA				–1.5	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –2 mA		2.4	3.3		V
V_{OL}		V_{CC} = 4.5 V,	I_{OL} = 12 mA			0.35	0.5	V
I_{OZH}	Outputs	V_{CC} = 5.5 V,	V_O = 2.7 V				20	µA
	I/O ports						100	
I_{OZL}	Outputs	V_{CC} = 5.5 V,	V_O = 0.4 V				–20	µA
	I/O ports						–250	
I_I	Pin 1, 11	V_{CC} = 5.5 V,	V_I = 5.5 V				0.2	mA
	All others						0.1	
I_{IH}	Pin 1, 11	V_{CC} = 5.5 V,	V_I = 2.7 V				50	µA
	I/O ports						100	
	All others						25	
I_{IL}		V_{CC} = 5.5 V,	V_I = 0.4 V				–0.25	mA
I_{OS}§		V_{CC} = 5.5 V,	V_O = 0.5 V		–30		–250	mA
I_{CC}		V_{CC} = 5.5 V,	V_I = 0,	Outputs open		170	220	mA

‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

§ Not more than one output should be shorted at a time and the duration of the short circuit should not exceed one second. Set V_O at 0.5 V to avoid test equipment degradation.

electrical characteristics over recommended operating free-air temperature range

PARAMETER		TEST CONDITIONS			TIBPAL16L8-15M TIBPAL16R6-15M TIBPAL16R8-15M			UNIT
					MIN	TYP†	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA				–1.5	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –2 mA		2.4	3.3		V
V_{OL}		V_{CC} = 4.5 V,	I_{OL} = 12 mA			0.35	0.5	V
I_{OZH}	Outputs	V_{CC} = 5.5 V,	V_O = 2.7 V				20	μA
	I/O ports						100	
I_{OZL}	Outputs	V_{CC} = 5.5 V,	V_O = 0.4 V				–20	μA
	I/O ports						–250	
I_I	Pin 1, 11	V_{CC} = 5.5 V,	V_I = 5.5 V				0.2	mA
	All others						0.1	
I_{IH}	Pin 1, 11	V_{CC} = 5.5 V,	V_I = 2.7 V				50	μA
	I/O ports						100	
	All others						20	
I_{IL}	I/O ports	V_{CC} = 5.5 V,	V_I = 0.4 V				–0.25	mA
	All others						–0.2	
I_{OS}‡		V_{CC} = 5.5 V,	V_O = 0.5 V		–30		–250	mA
I_{CC}		V_{CC} = 5.5 V,	V_I = 0,	Outputs open		170	220	mA

† All typical values are at V_{CC} = 5 V, T_A = 25°C.

‡ Not more than one output should be shorted at a time and the duration of the short circuit should not exceed one second. Set V_O at 0.5 V to avoid test equipment degradation.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
f_{max}§				50			MHz
t_{pd}	I, I/O	O, I/O			8	15	ns
t_{pd}	CLK↑	Q	R1 = 390 Ω,		7	12	ns
t_{en}	OE↓	Q	R2 = 750 Ω,		8	12	ns
t_{dis}	OE↑	Q	See Figure 1		7	12	ns
t_{en}	I, I/O	O, I/O			8	15	ns
t_{dis}	I, I/O	O, I/O			8	15	ns

† All typical values are at V_{CC} = 5 V, T_A = 25°C.

§ Maximum operating frequency and propagation delay are specified for the basic building block. When using feedback, limits must be calculated accordingly.

programming information

Texas Instruments programmable logic devices can be programmed using widely available software and inexpensive device programmers.

The TIBPAL16R4-15M with date codes prior to 9616A must be programmed according to programming algorithms/specifications corresponding to the TIBPAL16R4-12C. The TIBPAL16R4-15M with date code 9616A or newer must be programmed according to programming algorithms/specifications corresponding to the TIBPAL16R4-10C.

Regardless of date code, the TIBPAL16L8-15M, TIBPAL16R6-15M, and TIBPAL16R8-15M must be programmed according to programming algorithms/specifications corresponding to the TIBPAL16L8-12C, TIBPAL16R6-12C, and TIBPAL16R8-12C, respectively. Failure to do so may damage the devices.

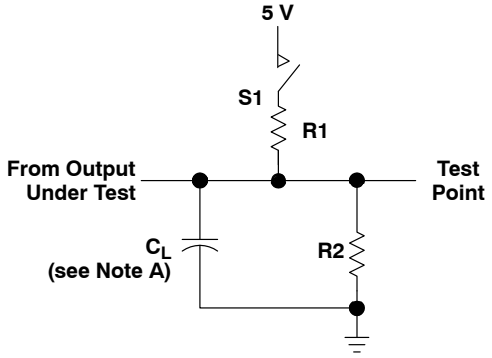
Complete programming specifications, algorithms, and the latest information on hardware, software, and firmware are available upon request. Information on programmers capable of programming Texas Instruments programmable logic is also available, upon request, from the nearest TI field sales office, local authorized TI distributor, or by calling Texas Instruments at (214) 997-5666.

Table 1. Programming Reference Table
(see Note 3)

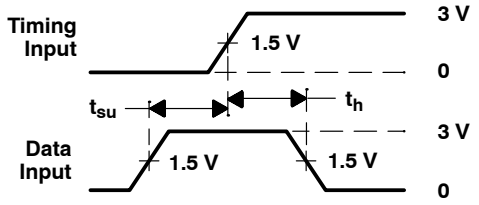
DEVICE	DESC SMD NUMBER	FAMILY/PINOUT CODE
TIBPAL16L8-15MJB	5962-8515509RA	9A/17
TIBPAL16L8-15MFKB	5962-85155092A	9A/717
TIBPAL16L8-15MWB	5962-8515509SA	9A/17
TIBPAL16R4-15MJB	5962-8515512RA	A1/24
TIBPAL16R4-15MFKB	5962-85155122A	0A1/724
TIBPAL16R4-15MWB	5962-8515512SA	A1/24
TIBPAL16R6-15MJB	5962-8515511RA	9A/24
TIBPAL16R6-15MFKB	5962-85155112A	9A/724
TIBPAL16R6-15MWB	5962-8515511SA	9A/24
TIBPAL16R8-15MJB	5962-8515510RA	9A/24
TIBPAL16R8-15MFKB	5962-85155102A	9A/724
TIBPAL16R8-15MWB	5962-8515510SA	9A/24

NOTE 3: Programming information for TIBPAL16R4-15M with date codes 9616A or newer. Programming information for TIBPAL16L8-15M, TIBPAL16R6-15M, and TIBPAL16R8-15M regardless of date code.

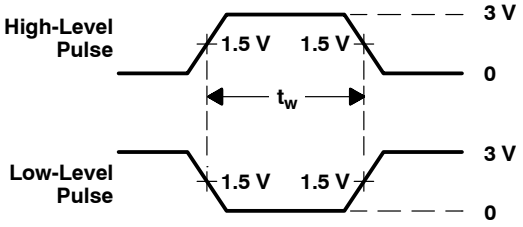
PARAMETER MEASUREMENT INFORMATION



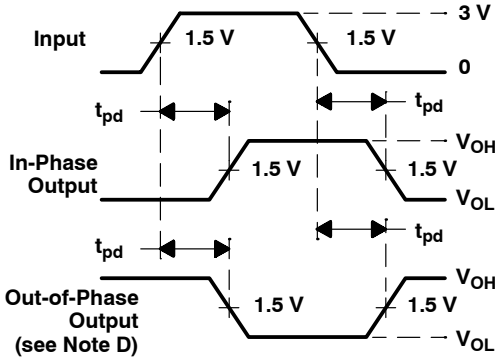
LOAD CIRCUIT FOR 3-STATE OUTPUTS



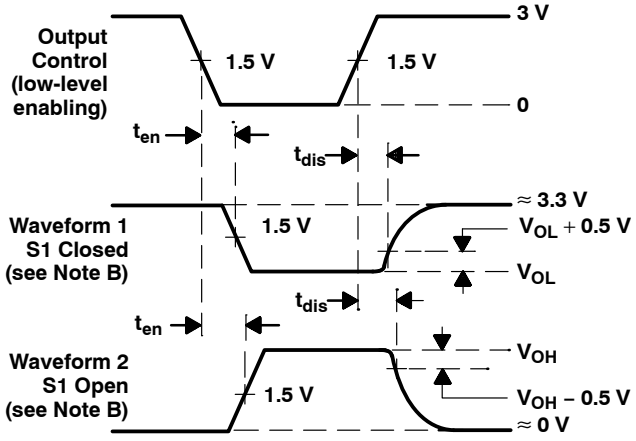
VOLTAGE WAVEFORMS SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS PULSE DURATIONS



VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

NOTES: A. C_L includes probe and jig capacitance and is 50 pF for t_{pd} and t_{en}, 5 pF for t_{dis}.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses have the following characteristics: PRR ≤ 10 MHz, t_r and t_f ≤ 2 ns, duty cycle = 50%.
D. When measuring propagation delay times of 3-state outputs, switch S1 is closed.
E. Equivalent loads may be used for testing.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/ Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
5962-85155092A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
5962-8515509RA	ACTIVE	CDIP	J	20	1	TBD	Call TI	Call TI	
5962-8515509SA	ACTIVE	CFP	W	20	1	TBD	Call TI	Call TI	
5962-85155102A	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	
5962-8515510RA	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI	
5962-8515510SA	OBSOLETE	CFP	W	20		TBD	Call TI	Call TI	
5962-85155112A	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	
5962-8515511RA	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI	
5962-8515511SA	OBSOLETE	CFP	W	20		TBD	Call TI	Call TI	
5962-85155122A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
5962-8515512RA	ACTIVE	CDIP	J	20	1	TBD	Call TI	Call TI	
5962-8515512SA	ACTIVE	CFP	W	20	1	TBD	Call TI	Call TI	
TIBPAL16L8-15MFKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
TIBPAL16L8-15MJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	
TIBPAL16L8-15MJB	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	
TIBPAL16L8-15MWB	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type	
TIBPAL16R4-15MFKB	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
TIBPAL16R4-15MJB	ACTIVE	CDIP	J	20	1	TBD	Call TI	Call TI	
TIBPAL16R4-15MWB	ACTIVE	CFP	W	20	1	TBD	Call TI	Call TI	
TIBPAL16R6-15MFKB	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	
TIBPAL16R6-15MJ	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI	
TIBPAL16R6-15MJB	OBSOLETE	CDIP	J	20		TBD	A42	N / A for Pkg Type	
TIBPAL16R6-15MWB	OBSOLETE	CFP	W	20		TBD	Call TI	Call TI	
TIBPAL16R8-15MFKB	OBSOLETE	LCCC	FK	20		TBD	POST-PLATE	N / A for Pkg Type	
TIBPAL16R8-15MJB	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI	
TIBPAL16R8-15MWB	OBSOLETE	CFP	W	20		TBD	Call TI	Call TI	

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

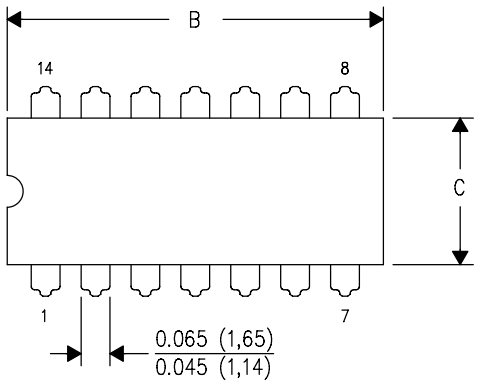
(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

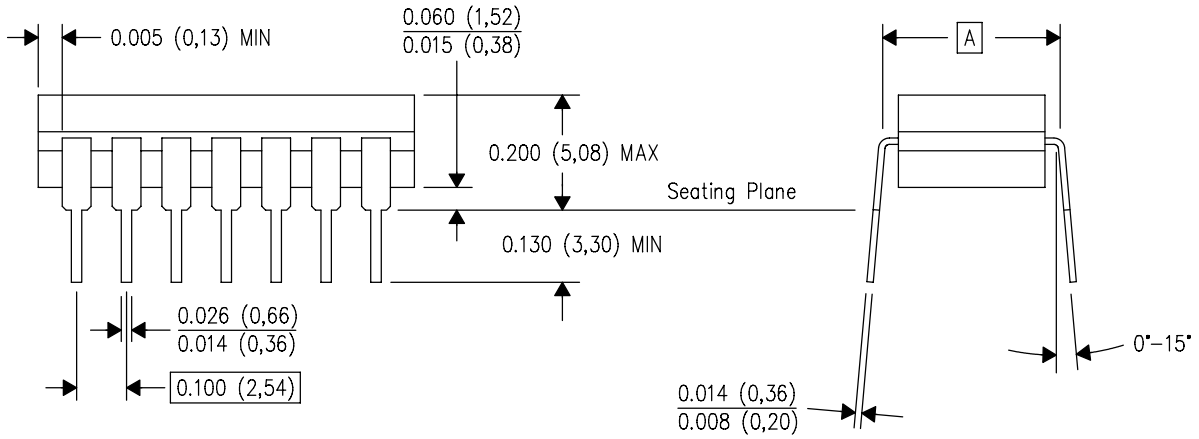
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



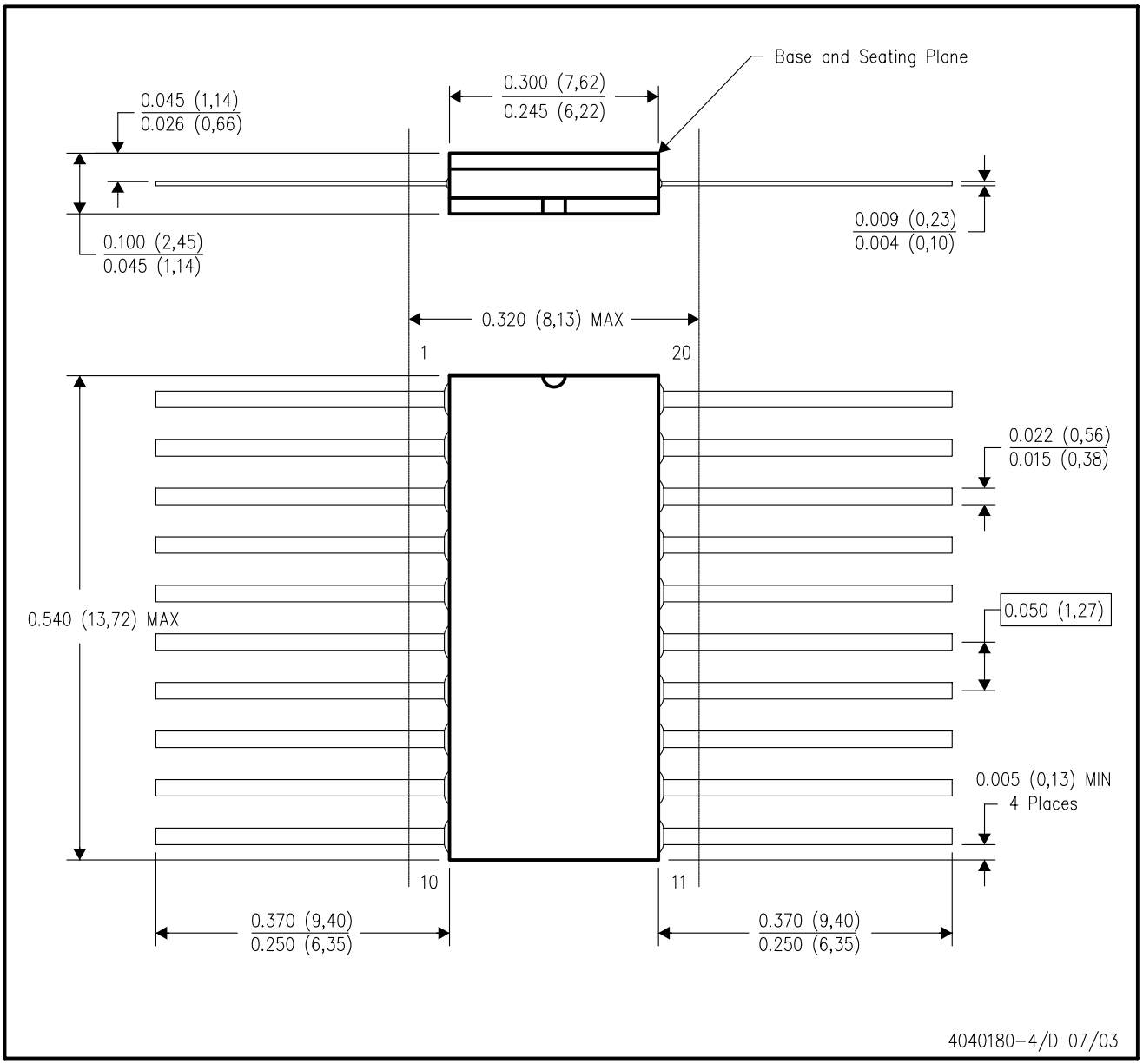
DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

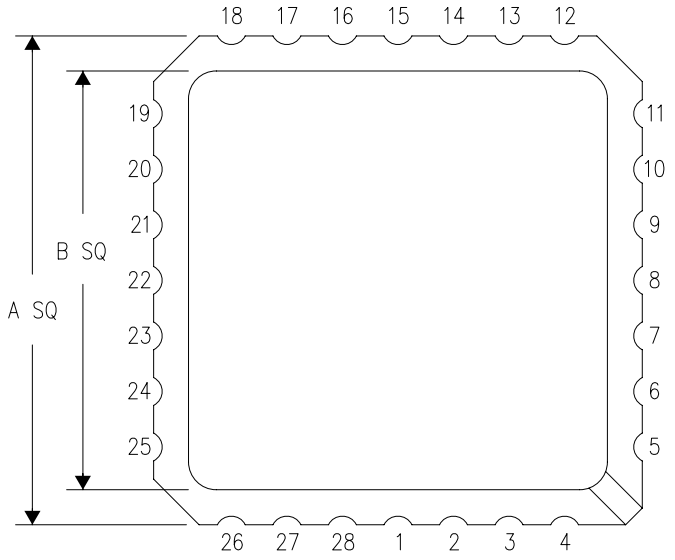
W (R–GDFP–F20) CERAMIC DUAL FLATPACK



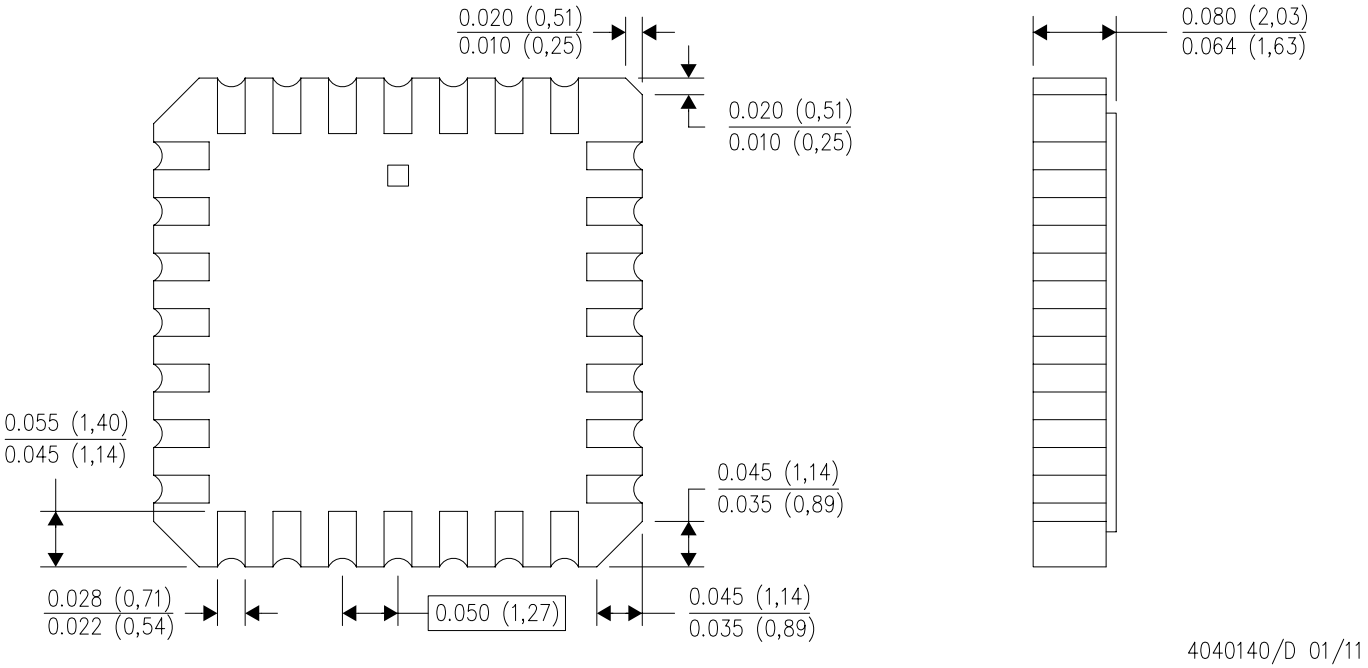
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within Mil–Std 1835 GDFP2–F20

FK (S–CQCC–N**) LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a metal lid.
D. Falls within JEDEC MS–004

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